

Product Change Notification / BLAS-28XZGK309

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13-May-2024

Product Category:

8-Bit Microcontrollers

PCN Type:

Manufacturing Change

Notification Subject:

CCB 6736 Final Notice: Qualification of palladium coated copper with gold flash (CuPdAu) as an additional bond wire material for selected ATMEGA1608, ATmega168PB, ATMEGA3208, ATmega328PB, ATMEGA4808, ATmega48PB, ATMEGA808, ATmega88PB and AVR16EB32 device families available in 32L VQFN (5x5x0.9mm) package at MP3A assembly site.

Affected CPNs:

BLAS-28XZGK309_Affected_CPN_05132024.pdf BLAS-28XZGK309_Affected_CPN_05132024.csv

Notification Text:

PCN Status:Final Notification

PCN Type:Manufacturing Change

Microchip Parts Affected:Please open one of the files found in the Affected CPNs section. Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change:Qualification of palladium coated copper with gold flash (CuPdAu) as an additional bond wire material for selected ATMEGA1608, ATmega168PB, ATMEGA3208, ATmega328PB, ATMEGA4808, ATmega48PB, ATMEGA808, ATmega88PB and AVR16EB32 device families available in 32L VQFN (5x5x0.9mm) package at MP3A assembly site.

Pre and Post Change Summary:

	Pre Change	Post C	ost Change				
	Microchip	Microchip	Microchip				
Assembly Site	Technology Inc.	Technology Inc.	Technology Inc.				
Assembly site	(MPHIL-3)	(MPHIL-3)	(MPHIL-3)				
	(MP3A)	(MP3A)	(MP3A)				
Wire Material	Au	Au	CuPdAu				
Die Attach Material	3280	3280	3280				
Molding Compound Material	G700LTD	G700LTD	G700LTD				
Lead-Frame Material	C194	C194	C194				

Impacts to Data Sheet:None

Change ImpactNone

Reason for Change:To improve productivity and on-time delivery performance by qualifying palladium coated copper with gold flash (CuPdAu) as an additional bond wire material at MP3A assembly site.

Change Implementation Status:In Progress

Estimated First Ship Date: June 7, 2024 (date code: 2423)

Note: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Time Table Summary:

	February 2024			>	May 2024				June 2024							
Workweek	05	06	07	08	09		18	19	20	21	22	23	24	25	26	27
Initial PCN Issue Date	Х															
Qual Report Availability									Х							
Final PCN Issue Date									Х							
Estimated Implementation Date												Х				

Method to Identify Change:Traceability code

Qualification Report:Please open the attachments included with this PCN labeled as PCN_#_Qual_Report.

Revision History:February 01, 2024: Issued initial notification.

May 13, 2024: Issued final notification. Attached the Qualification Report. Provided estimated first ship date to be on June 7, 2024.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachments:

PCN_BLAS-28XZGK309_Qual Report.pdf

Please contact your local Microchip sales office with questions or concerns regarding this notification.

Terms and Conditions:

If you wish to <u>receive Microchip PCNs via email</u> please register for our PCN email service at our <u>PCN</u> home page select register then fill in the required fields. You will find instructions about registering for Microchips PCN email service in the <u>PCN FAQ</u> section.

If you wish to <u>change your PCN profile</u>, <u>including opt out</u>, please go to the <u>PCN home page</u> select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.

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Affected Catalog Part Numbers (CPN)

ATMEGA1608-MUR

ATMEGA1608-MF

ATMEGA1608-MFR

ATMEGA1608-MU

ATMEGA3208-MF

ATMEGA3208-MFR

ATMEGA3208-MU

ATMEGA3208-MUR

ATMEGA808-MF

ATMEGA808-MU

ATMEGA808-MUR

ATMEGA808-MFR

ATMEGA4808-MF

ATMEGA4808-MUR

ATMEGA4808-MU

ATMEGA168PB-MU

ATMEGA168PB-MN

ATMEGA168PB-MNR

ATMEGA168PB-MUR

ATMEGA88PB-MU

ATMEGA48PB-MU

ATMEGA88PB-MN

ATMEGA48PB-MN

ATMEGA88PB-MNR

ATMEGA48PB-MNR

ATMEGA88PB-MUR

ATMEGA48PB-MUR

ATMEGA328PB-MU

ATMEGA328PB-MN

ATMEGA328PB-MNR

ATMEGA328PB-MUR

ATMEGA4808-MFR

AVR16EB32-E/RXB AVR16EB32-I/RXB

AVR16EB32T-I/RXB

AVR16EB32T-E/RXB

Date: Sunday, May 12, 2024